

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-15 (cancelled)

16. (currently amended) A ball film for fabricating and/or testing integrated circuits, comprising:

a thin film having a front side and a back side comprising a plurality of slots;

each slot having a opening having a first diameter on the front side and a  
opening with a second diameter on the back side of the thin film, a side wall including a  
portion of a sphere with a diameter greater than the first and the second diameter; and

a plurality of metal balls each movably contained within a respective one of the plurality of slots; each ball having a diameter greater than the first and the second  
diameter of the slot containing the ball.

17. (canceled)

18. (currently amended) The ball film of Claim 16, wherein the thin film is formed from two separate thin films of material.

19. (original) The ball film of Claim 16, wherein the thin film is formed from polyimide.

20. (original) The ball film of Claim 16, wherein the metal balls are formed from solder.

21. (original) The ball film of Claim 16, wherein the thin film comprises a thickness of between 0.01 mm and 0.4 mm.

22. (original) The ball film of Claim 16, wherein the metal balls each have a diameter of between 0.1 mm and 0.5 mm.

23-28 (cancelled)

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29. (new) The ball film of Claim 16, in which the portion of a sphere comprises a first portion of a sphere with a diameter greater than the first diameter and a second portion of a sphere with a diameter greater than the second diameter.